

Title (en)

Method for manufacturing an electronic element

Title (de)

Verfahren zur Herstellung eines elektronischen Bauteils

Title (fr)

Méthode pour la fabrication d'un élément électronique

Publication

EP 1621053 A1 20060201 (DE)

Application

EP 04730954 A 20040504

Priority

- DE 2004000935 W 20040504
- DE 10320090 A 20030505

Abstract (en)

[origin: DE10320090A1] Electronic assembly, especially a printed circuit board, has electronic components (1-3) that are connected via electrical contacts (6) and a conducting region (7) made from plastic (11) that has conductor tracks (8) made from carbonized plastic and or agglomerated nano-particles. The conductor tracks are connected to the component contacts (6) or external contacts (9). Independent claims are also included for the following:- (a) a device for manufacture of a circuit board with carbonized plastic conductor tracks and; (b) a method of manufacture of a circuit board with carbonized plastic conductor tracks.

IPC 1-7

H05K 3/10; H05K 3/46; H05K 1/00; H01R 3/00

IPC 8 full level

H01L 21/98 (2006.01); **H01L 23/498** (2006.01); **H01L 23/538** (2006.01); **H01L 25/065** (2006.01); **H05K 3/10** (2006.01); **H05K 1/18** (2006.01)

CPC (source: EP US)

H01L 23/49883 (2013.01 - EP US); **H01L 23/5389** (2013.01 - EP US); **H01L 24/24** (2013.01 - EP US); **H01L 24/82** (2013.01 - EP US); **H01L 25/0652** (2013.01 - EP US); **H01L 25/50** (2013.01 - EP US); **H05K 3/105** (2013.01 - EP US); **H01L 2224/24011** (2013.01 - EP US); **H01L 2224/82103** (2013.01 - EP US); **H01L 2924/01004** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01011** (2013.01 - EP US); **H01L 2924/01032** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01039** (2013.01 - EP US); **H01L 2924/01057** (2013.01 - EP US); **H01L 2924/01068** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/19041** (2013.01 - EP US); **H05K 1/185** (2013.01 - EP US); **H05K 2201/0257** (2013.01 - EP US); **H05K 2201/0323** (2013.01 - EP US); **H05K 2203/0285** (2013.01 - EP US); **H05K 2203/102** (2013.01 - EP US); **H05K 2203/107** (2013.01 - EP US); **H05K 2203/1136** (2013.01 - EP US); **Y10S 977/773** (2013.01 - EP US)

Citation (search report)

See references of WO 2004100628A1

Designated contracting state (EPC)

DE

DOCDB simple family (publication)

DE 10320090 A1 20040826; EP 1621053 A1 20060201; EP 1621053 B1 20130102; US 2007113305 A1 20070517; US 7709379 B2 20100504; WO 2004100628 A1 20041118

DOCDB simple family (application)

DE 10320090 A 20030505; DE 2004000935 W 20040504; EP 04730954 A 20040504; US 55563204 A 20040504